

STGF14N60D STGP14N60D

14 A - 600 V - short circuit rugged IGBT

Preliminary Data

Features

- Low on-voltage drop (V_{CE(sat)})
- Operating junction temperature up to 175 °C
- Low C_{res} / C_{ies} ratio (no cross conduction susceptibility)
- Tight parameter distribution
- Ultra fast soft recovery antiparallel diode
- Short circuit rugged

Applications

- Motor drives
- High frequency inverters
- SMPS and PFC in both hard switch and resonant topologies



This IGBT utilizes the advanced PowerMESH™ process resulting in an excellent trade-off between switching performance and low on-state behavior.

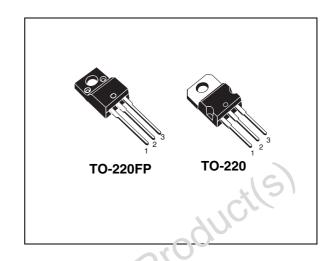


Figure 1. Internal schematic diagram

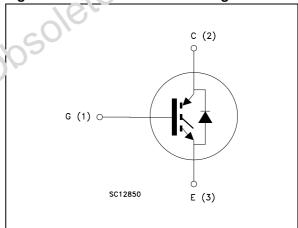


Table : Device summary

Order codes Marking		Package	Packaging
STGF14N60D	GF14N60D	TO-220FP	Tube
STGP14N60D	STGP14N60D GP14N60D		Tube

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1 Electrical ratings

Table 2. Absolute maximum ratings

Cumbal	Powers at a second	Value	11	
Symbol	Parameter	TO-220	TO-220FP	Unit
V _{CES}	Collector-emitter voltage (V _{GE} = 0)	600		V
I _C ⁽¹⁾	Collector current (continuous) at T _C = 25 °C	25	11	Α
I _C ⁽¹⁾	Collector current (continuous) at T _C = 100 °C	14	7	Α
I _{CL} (2)	Turn-off latching current	50		Α
I _{CP} ⁽³⁾	Pulsed collector current 50			Α
V _{GE}	Gate-emitter voltage ±20		V	
I _F	Diode RMS forward current at T _C = 25 °C 20		Α	
I _{FSM}	Surge non repetitive forward current t _p = 10 ms sinusoidal	55	Cili	Α
V _{ISO}	Insulation withstand voltage (RMS) from all three leads to external hea sink (t=1 s; T _C = 25 °C)		V	
P _{TOT}	Total dissipation at T _C = 25 °C 95 3		33	W
t _{scw}	Short circuit withstand time, $V_{CE} = 0.5V_{(BR)CES}$, $T_{C} = 125$ °C, $R_{G} = 10 \Omega$, $V_{GE} = 15 V$		μs	
T _j	Operating junction temperature	– 40 to	175	ô

1. Calculated according to the iterative formula:

$$I_{C}(T_{C}) = \frac{T_{j(max)} - T_{C}}{R_{thj-c} \times V_{CE(sat)(max)}(T_{j(max)}, \ I_{C}(T_{C}))}$$

- 2. Vclamp = 80% of V_{CES} , T_j =175 °C, R_G =10 Ω , V_{GE} =15 V
- 3. Pulse width limited by max. junction temperature allowed

Table 3. Thermal resistance

Symbol	Parameter	Valu	Unit	
Symbol	raiametei	TO-220	TO-220FP	Oiiii
R _{thj-case}	Thermal resistance junction-case IGBT max.	1.56	4.5	°C/W
R _{thj-case}	Thermal resistance junction-case diode max.	2.2	5.6	°C/W
R _{thj-amb}	Thermal resistance junction-ambient max.	62.5		°C/W

2 **Electrical characteristics**

(T_{CASE}=25 °C unless otherwise specified)

Table 4. **Static**

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)CES}	Collector-emitter breakdown voltage (V _{GE} = 0)	I _C = 1 mA	600			V
V _{CE(sat)}	Collector-emitter saturation voltage	V _{GE} = 15 V, I _C = 7 A V _{GE} = 15 V, I _C = 7 A, T _C = 125 °C		2.1 1.8		V V
V _{GE(th)}	Gate threshold voltage	V _{CE} = V _{GE} , I _C = 250 μA	4.5		6.5	٧
I _{GES}	Gate-emitter leakage current (V _{CE} = 0)	V _{GE} = ±20 V, T _C = 125 °C			±100	nA
I _{CES}	Collector cut-off current (V _{GE} = 0)	V _{CE} = 600 V V _{CE} = 600 V, T _C = 125 °C			150 1	μA mA
g _{fs} ⁽¹⁾	Forward transconductance	$V_{CE} = 15 \text{ V}, I_{C} = 7 \text{ A}$		3.2		S
 Pulsed: Pulse duration = 300 μs, duty cycle 1.5% Table 5. Dynamic 						
Cymbol	Doromotor	Toot conditions	Min	Typ	Mov	Hait

^{1.} Pulsed: Pulse duration = 300 μs, duty cycle 1.5%

Table 5. **Dynamic**

Tubic o.	Dynamio					
Symbol Paran		Test conditions	Min.	Тур.	Max.	Unit
C _{ies} C _{oes} C _{res}	Input capacitance Output capacitance Reverse transfer capacitance	$V_{CE} = 25 \text{ V}, f = 1 \text{ MHz}, V_{GE} = 0$		TBD TBD TBD		pF pF pF
Qg	Total gate charge	$V_{CE} = 390 \text{ V}, I_{C} = 7 \text{ A},$		TBD		nC
Q _{ge} Q _{gc}	Gate-emitter charge Gate-collector charge	V _{GE} = 15 V (see Figure 3)		TBD TBD		nC nC
eteP	, codio					

Table 6. Switching on/off (inductive load)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)} t _r (di/dt) _{on}	Turn-on delay time Current rise time Turn-on current slope	V_{CC} = 390 V, I_{C} = 7 A R_{G} = 10 Ω V _{GE} = 15 V, (see Figure 2)		TBD TBD TBD		ns ns A/µs
t _{d(on)} t _r (di/dt) _{on}	Turn-on delay time Current rise time Turn-on current slope	V_{CC} = 390 V, I_{C} = 7 A R_{G} = 10 Ω V _{GE} = 15 V, T_{C} = 125 °C (see Figure 2)		TBD TBD TBD		ns ns A/µs
$t_r(V_{off})$ $t_d(_{off})$ t_f	Off voltage rise time Turn-off delay time Current fall time	V_{CC} = 390 V, I_{C} = 7 A, R_{GE} = 10 Ω V _{GE} = 15 V (see Figure 2)		TBD TBD TBD		ns ns ns
t _r (V _{off}) t _d (_{off}) t _f	Off voltage rise time Turn-off delay time Current fall time	V_{CC} = 390 V, I_{C} = 7 A, R_{GE} = 10 Ω , V_{GE} = 15 V T_{C} = 125 °C (see Figure 2)		TBD TBD TBD	(S	ns ns ns

Table 7. Switching energy (inductive load)

Symbol	Parameter	Test conditions	Min	Тур.	Max	Unit
Eon ⁽¹⁾ E _{off} ⁽²⁾ E _{ts}	Turn-on switching losses Turn-off switching losses Total switching losses	V_{CC} = 390 V, I_{C} = 7 A R_{G} = 10 Ω V _{GE} = 15 V, (see Figure 2)		TBD TBD TBD		μJ μJ μJ
Eon ⁽¹⁾ E _{off} ⁽²⁾ E _{ts}	Turn-on switching losses Turn-off switching losses Total switching losses	V_{CC} = 390 V, I_{C} = 7 A R_{G} = 10 Ω , V_{GE} = 15 V, T_{C} = 125 °C (see Figure 2)		TBD TBD TBD		μJ μJ μJ

Eon is the turn-on losses when a typical diode is used in the test circuit. If the IGBT is offered in a package with a co-pack diode, the co-pack diode is used as external diode. IGBTs and DIODE are at the same temperature (25°C and 125°C)

Table 8. Collector-emitter diode

Symbol	Parameter	Test conditions	Min	Тур.	Max	Unit
V _F	Forward on-voltage	I _F = 7 A I _F = 7 A, T _C = 125 °C		1.8 1.3	2.1	V V
t _{rr} Q _{rr} I _{rrm}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_F = 7 \text{ A}, V_R = 40 \text{ V},$ di/dt = 100 A/ μ s (see Figure 5)		37 40 2.1		ns nC A
t _{rr} Q _{rr} I _{rrm}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_F = 7 \text{ A}, V_R = 40 \text{ V},$ $T_{C} = 125 ^{\circ}\text{C},$ $di/dt = 100 \text{ A/}\mu\text{s}$ (see Figure 5)		61 98 3.2		ns nC A

^{2.} Turn-off losses include also the tail of the collector current.

3 Test circuit

Figure 2. Test circuit for inductive load switching

Figure 3. Gate charge test circuit

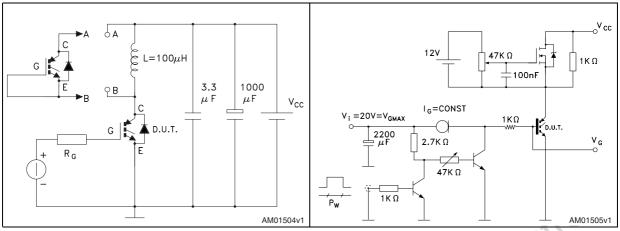
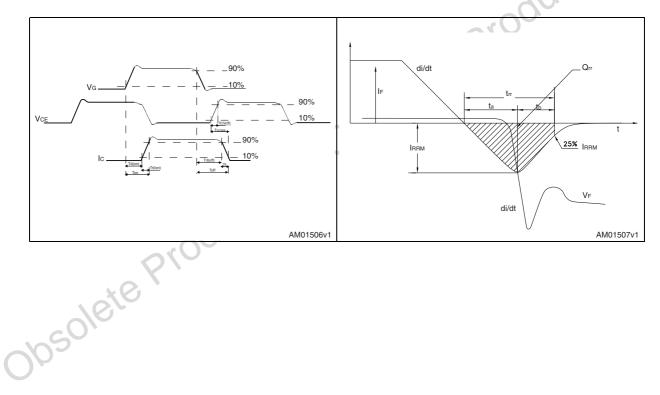


Figure 4. Switching waveforms

Figure 5. Diode recovery times waveform



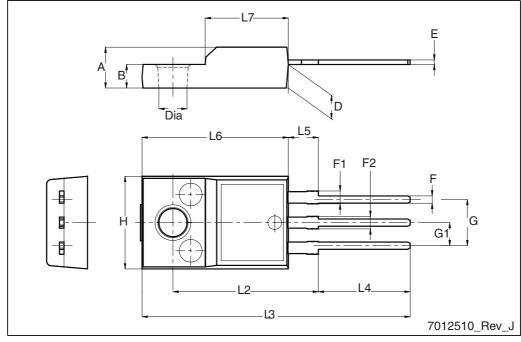
4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

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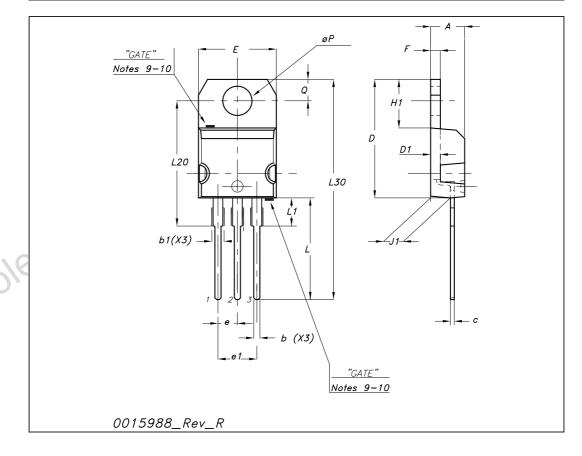
TO-220FP mechanical data

Dim.		mm				
Dilli.	Min.	Тур.	Max.			
А	4.4		4.6			
В	2.5		2.7			
D	2.5		2.75			
Е	0.45		0.7			
F	0.75		1			
F1	1.15		1.70			
F2	1.15		1.5			
G	4.95		5.2			
G1	2.4		2.7			
Н	10		10.4			
L2		16				
L3	28.6		30.6			
L4	9.8		10.6			
L5	2.9		3.6			
L6	15.9		16.4			
L7	9		9.3			
Dia	3		3.2			



TO-220 mechanical data

Dim		mm			inch	
Dim	Min	Тур	Max	Min	Тур	Max
А	4.40		4.60	0.173		0.181
b	0.61		0.88	0.024		0.034
b1	1.14		1.70	0.044		0.066
С	0.48		0.70	0.019		0.027
D	15.25		15.75	0.6		0.62
D1		1.27			0.050	
E	10		10.40	0.393		0.409
е	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.194		0.202
F	1.23		1.32	0.048		0.051
H1	6.20		6.60	0.244		0.256
J1	2.40		2.72	0.094		0.107
L	13		14	0.511		0.551
L1	3.50		3.93	0.137		0.154
L20		16.40			0.645	
L30		28.90			1.137	İ
ØP	3.75		3.85	0.147		0.151
Q	2.65	ĺ	2.95	0.104		0.116



5 Revision history

Table 9. Document revision history

Date	Revision	Changes
20-Feb-2009	1	Initial release.

Obsolete Product(s) - Obsolete Product(s)

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